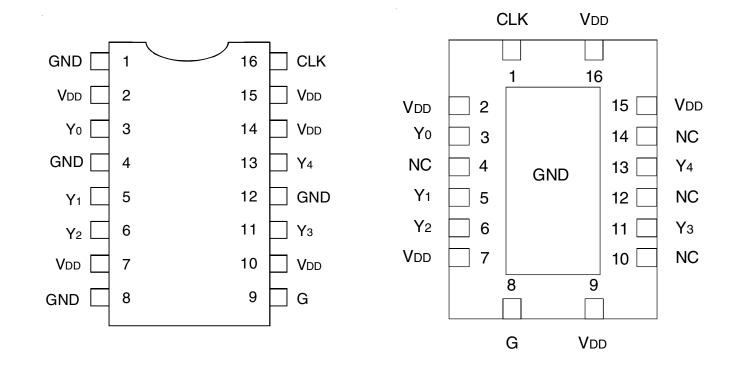
PIN CONFIGURATION



TSSOP TOP VIEW VFQFPN TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
Vdd	Power Supply Voltage	-0.5 to +4.6	V
Vi	Input Voltage ⁽²⁾	-0.5 to VDD +0.5	V
Vo	Output Voltage ⁽²⁾	-0.5 to VDD +0.5	V
Ік	Input Clamp Current VI < 0 or VI > VDD	±50	mA
Іок	Output Clamp Current Vo < 0 or Vo > VoD	±50	mA
lo	Continuous Total Output Current Vo < 0 to VDD	±50	mA
Tstg	Storage Temperature	-65 to +150	°C

NOTES:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. Not to exceed 4.6V.

CAPACITANCE(TA = +25°C, f = 1MHz, VIN = 0V)

Parameter	Description	Min.	Тур.	Max.	Unit
CIN	Input Capacitance	-	2.5	_	pF
	$V_I = 0V \text{ or } V_{DD}$				

FUNCTION TABLE⁽¹⁾

Inp	outs	Output
G	CLK	Y(0:4)
L	Х	L
Н	Н	Н

NOTE:

1. H = HIGH Voltage Level

L = LOW Voltage Level

X = Don't Care

PIN DESCRIPTION

TERMINAL			
Symbol I/O Description		Description	
G	Ι	I Output Enable Control for Y(0:4) Outputs. This output enable is active HIGH. If this pin is Logic HIGH, the Y(0:4) clock outputs will fo input clock (CLK). If this pin is logic LOW, the Y(0:4) outputs will drive low independent of the state of CLK.	
Y(0:4)	0	Buffered Output Clocks	
CLK	I	Input Reference Frequency	
GND		Ground	
Vdd	PWR	DC Power Supply, 2.3V to 3.6V	

RECOMMENDED OPERATING RANGE

Symbol	Description		Min.	Тур.	Max.	Unit
Vdd	Internal Power Supply Voltage		2.3	2.5		V
				3.3	3.6	
VIL	Input Voltage LOW	VDD = 3V to 3.6V			0.8	V
		VDD = 2.3V to 2.7V			0.7	
Vih	Input Voltage HIGH	VDD = 3V to 3.6V	2			V
		VDD = 2.3V to 2.7V	1.7			
VI	Input Voltage		0		Vdd	V
Іон	Output Current HIGH	VDD = 3V to 3.6V			-12	mA
		VDD = 2.3V to 2.7V			-6	
Iol	Output Current LOW	VDD = 3V to 3.6V			12	mA
		VDD = 2.3V to 2.7V			6	
TA	Ambient Operating Temperature		-40		+85	°C

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Unit
Vik	InputVoltage	$V_{DD} = 3V$, $I_{IN} = -18mA$			- 1.2	V
lin	Input Current	$V_I = 0V \text{ or } V_{DD}$			±5	μA
ldd	Static Device Current ⁽¹⁾	$CLK = 0V \text{ or } V_{DD}, \text{ Io} = 0mA, V_{DD} = 3.3V$			25	μA

NOTE:

1. For IDD over frequency, see TEST CIRCUIT AND WAVEFORMS.

DC ELECTRICAL CHARACTERISTICS - VDD = 3.3V ± 0.3V

Symbol	Parameter	Test Cor	nditions	Min.	Typ. ⁽¹⁾	Max	Unit
		VDD = Min. to Max.	Іон = -100μА	Vdd - 0.2			
Vон	HIGH level Output Voltage	Vdd = 3V	Iон = -12mA	2.1			V
			Іон = -6mA	2.4			
		VDD = Min. to Max.	Іон = 100μА			0.2	
Vol	LOW level Output Voltage	Vdd = 3V	Iон = 12mA			0.8	V
			Іон = 6mA			0.55	
		Vdd = 3V	Vo = 1V	-28			
Іон	HIGH level Output Current	VDD = 3.3V	Vo = 1.65V		-36		mA
		VDD = 3.6V	Vo = 3.135V			-14	
		VDD = 3V	Vo = 1.95V	28			
Iol	LOW level Output Current	$V_{DD} = 3.3V$	Vo = 1.65V		36		mA
		$V_{DD} = 3.6V$	Vo = 0.4V			14	

NOTE:

1. All typical values are at respective nominal V $_{\text{DD.}}$

DC ELECTRICAL CHARACTERISTICS - $V_{DD} = 2.5V \pm 0.2V$

Symbol	Parameter	Test Con	ditions	Min.	Тур.(1)	Max	Unit
Vон	HIGH level Output Voltage	VDD = Min. to Max.	Іон = -100μА	Vdd - 0.2			V
		VDD = 2.3V	Iон = -6mA	1.8			
Vol	LOW level Output Voltage	VDD = Min. to Max.	Іон = 100μА			0.2	V
		VDD = 2.3V	Iон = 6mA			0.55	
		VDD = 2.3V	Vo = 1V	-17			
Іон	HIGH level Output Current	$V_{DD} = 2.5V$	Vo = 1.25V		-25		mA
		VDD = 2.7V	Vo = 2.375V			-10	
		$V_{DD} = 2.3V$	Vo = 1.2V	17			
Iol	LOW level Output Current	Vdd = 2.5V	Vo = 1.25V		25		mA
		Vdd = 2.7V	Vo = 0.3V			10	

NOTE:

1. All typical values are at respective nominal VDD.

TIMING REQUIREMENTS OVER RECOMMENDED RANGE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max	Unit
fcl.k	Clock Frequency	$V_{DD} = 3V$ to $3.6V$	0		200	MHz
		VDD = 2.3V to 2.7V	0		170	

SWITCHING CHARACTERISTICS OVER OPERATING RANGE -

$V_{DD} = 3.3V \pm 0.3V^{(1)}$

Symbol	Parameter	Test Conditions	Min.	Тур. ⁽¹⁾	Max	Unit
t PLH	CLK to Yx	f = 0MHz to 200MHz, CL = 25pF	1.3		2.6	ns
t PHL						
tsk(o) ⁽²⁾	Output Skew, Yx to Yx				75	ps
tsk(p)	Pulse Skew				200	ps
tsk(pp)	Part-to-Part Skew				500	ps
tR	RiseTime	$Vo = 0.4V$ to $2V^{(3)}$	1.0		2.3	V/ns
tr	FallTime	$Vo = 2V \text{ to } 0.4V^{(3)}$	1.0		2.3	V/ns
ts∪	G before CLK↓	V(THRESHOLD) = VDD/2	0.1			ns
tH	G after CLK↓		0.4			

NOTES:

1. All typical values are at respective nominal VDD.

2. This specification is only valid for equal loading of all outputs.

3. Measured at 100MHz.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE -

$V_{DD} = 2.5V \pm 0.2V^{(1)}$

Symbol	Parameter	Test Conditions	Min.	Typ. ⁽¹⁾	Max	Unit
t PLH	CLK to Yx	f = 0MHz to 170MHz, CL = 25pF	1.5		3	ns
t PHL						
tsk(o) ⁽²⁾	Output Skew, Yx to Yx				100	ps
tsk(p)	Pulse Skew				350	ps
tsk(pp)	Part-to-Part Skew				600	ps
tR	RiseTime	Vo = 0.4V to 1.7V ⁽³⁾	0.4		1.625	V/ns
ŀ	FallTime	Vo = 1.7V to 0.4V ⁽³⁾	0.4		1.625	V/ns
tsu	G before CLK↓	V(THRESHOLD) = VDD/2	0.1			ns
tH	G after CLK↓		0.4]

NOTES:

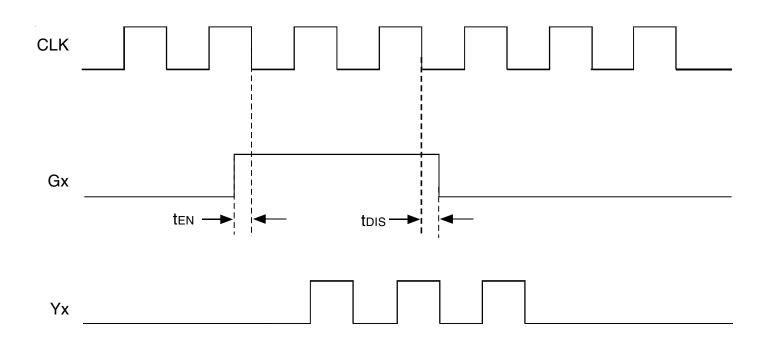
1. All typical values are at respective nominal VDD.

2. This specification is only valid for equal loading of all outputs.

3. Measured at 100MHz.

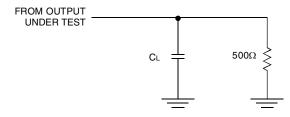
OUTPUT ENABLE GLITCH SUPPRESSION CIRCUIT

The purpose of the glitch suppression circuitry is to ensure the output enable sequence is synchronized with the clock input such that the output buffer will be enabled on the next full period of the input clock (negative edge triggered by the input clock). The G input must be stable one ten - time prior to the falling edge of the CLK for predictable operation.



G (ten, tois) Relative to CLK↓

TEST CIRCUITS AND WAVEFORMS

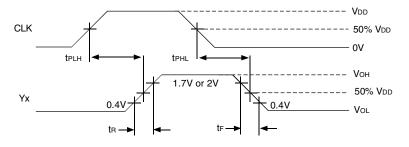


NOTES:

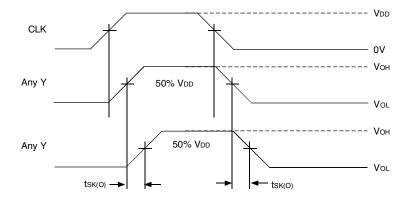
1. CL includes probe and jig capacitance.

2. All input pulses are supplied by generators having the following characteristics: PRR \leq 200MHz; Zo = 50 Ω ; tr < 1.2ns; tr < 1.2ns.

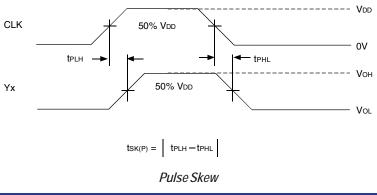
Test Load Circuit



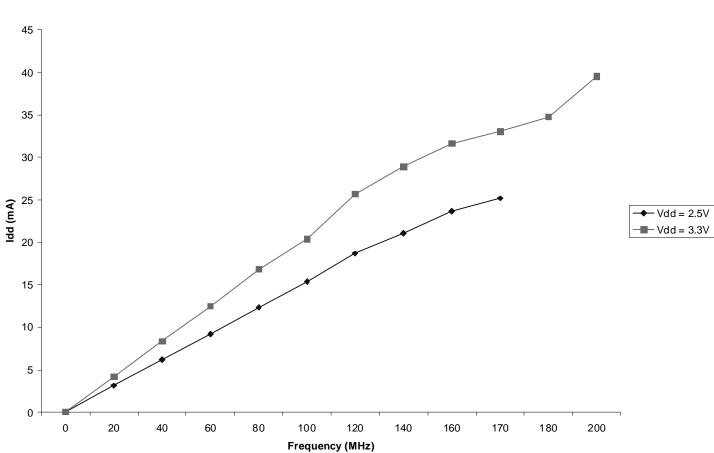
Voltage Waveforms Propagation Delay Times



Output Skew

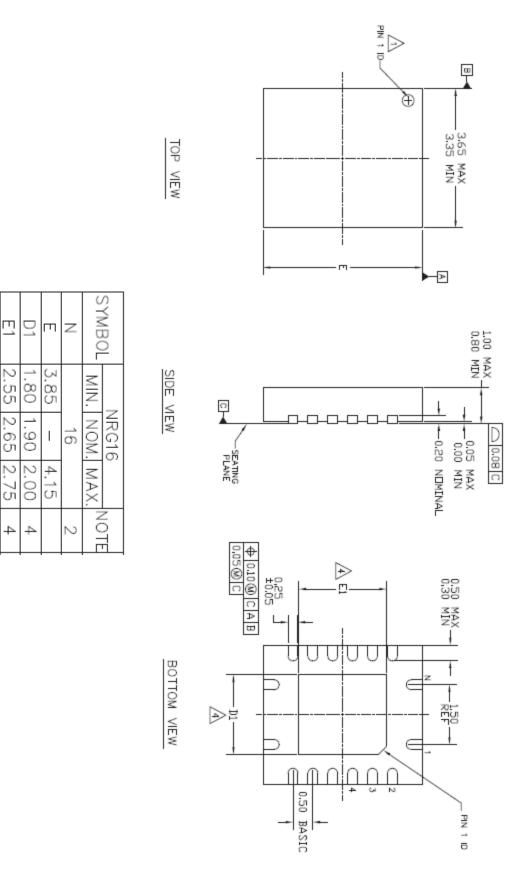


TEST CIRCUITS AND WAVEFORMS (cont.)



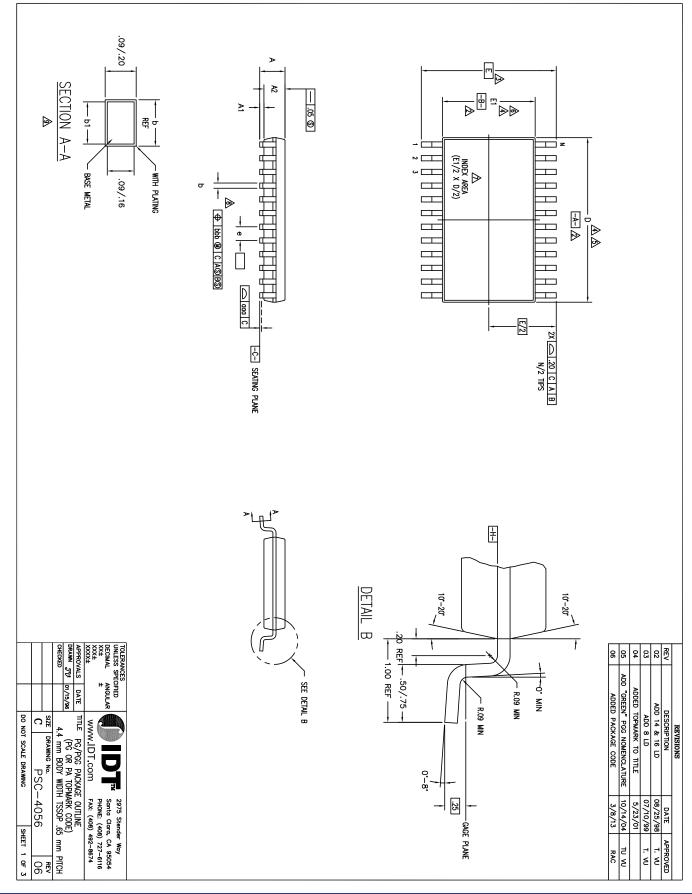
Idd vs Frequency

PACKAGE DRAWINGS AND DIMENSIONS - 16VFQFPN



NRG16

PACKAGE DRAWINGS AND DIMENSIONS - 16TSSOP



PACKAGE DRAWINGS AND DIMENSIONS - 16TSSOP (cont.)

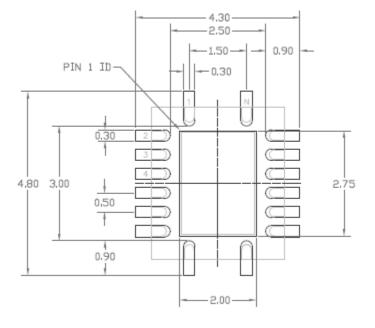
		PG/PGG16						
SYMBOL	JEDE	JEDEC VARIATION						
B		AB						
L	MIN	NOM	MAX	Ē				
Α	-	-	1.20					
A1	.05	-	.15					
A2	.80	1.00	1.05					
D	4.90	5.00	5.10	4,5				
Ε	(6.40 BSC	,	3				
E1	4.30	4.40	4.50	4,6				
е		.65 BSC						
b	.19	-	.30					
b1	.19	.22	.25					
aaa	-	-	.10					
bbb	10							
Ν		16						

NOTES:

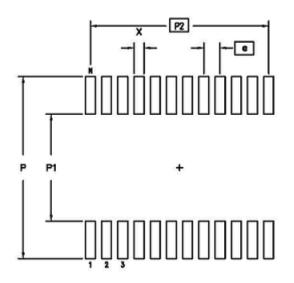
- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994
- ▲ DATUMS —A— AND —B— TO BE DETERMINED AT DATUM PLANE —H—
- ▲ DIMENSION E TO BE DETERMINED AT SEATING PLANE -C-
- ▲ DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE __H_
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- 10 ALL DIMENSIONS ARE IN MILLIMETERS
- 11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION AA, AB-1, AB, AC, AD & AE

RECOMMENDED LANDING PATTERNS

NOTE: All dimensions are in millimeters.



NR 16 pin



	MIN	MAX	
Ρ	7.20	7.40	
P1	4.20	4.40	
P2	4.55 BSC		
X	.30	.50	
e	.65 BSC		
N	16		

16 TSSOP

ORDERING INFORMATION

Part/Order Number	Shipping Packaging	Package	Temperature
5V2305PGGI	Tubes	16-pin TSSOP	-40° to +85°C
5V2305PGGI8	Tape and Reel	16-pin TSSOP	-40° to +85°C
5V2305NRGI	Tubes	16-pin VFQFPN	-40° to +85°C
5V2305NRGI8	Tape and Reel	16-pin VFQFPN	-40° to +85°C

"G" suffix to the part number denotes Pb-free configuration, RoHS compliant.

REVISION HISTORY

August 11, 2014Pg. 5; Changed Rise/Fall Time minimum specs in 3.3V Swtiching Characteristics table from 0.7V/ns to 1.0V/nsSeptember 25, 2014Added 16TSSOP landing pattern and 16VFQFPN/TSSOP package drawings

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